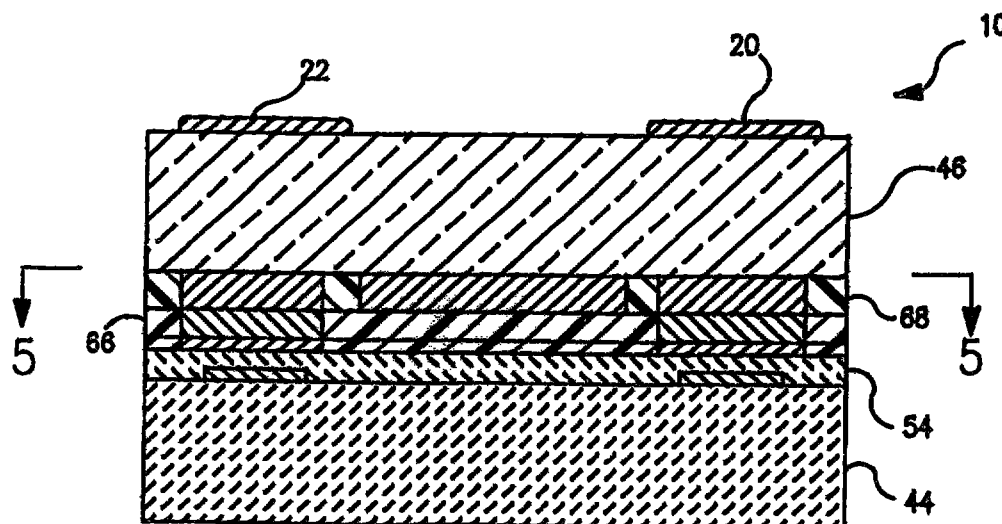




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(54) Title: SURFACE MOUNT LC FILTER WITH POLYMER LAYERS



(57) Abstract

A surface mount filter (10) has a device body with a plurality of terminations (20, 22) located thereon. The device body is constructed having a rigid insulative substrate (44) with a first conductive pattern having one or more first capacitor plates which is opposed by a second conductive layer defining second capacitor plates on a dielectric layer (54). One or more layers of insulative polymer (66, 68) are located above the dielectric layer (54) and have conductor channels in which conductive material is located which forms the coil of the inductor. A sealing cover (46) such as glass or a planar polymeric sheet is located above the polymer layers. The chip is preferably built by thin film technology which allows a considerable reduction in component or circuit size for a variety of LC filters, such as LPF, HPF, BPF, BRPF, or combinations thereof as well as LC resonators.